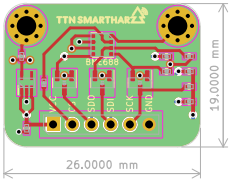


BME288 Breakout Board

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.5900 mm
Board overall dimensions:	26.1000 mm x 19.1000 mm		
Min track/spacing:	0.2000 mm / 0.0000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	HAL lead-free	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		



Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Black	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.2 mm		4.5	0.02
GND	copper		0.0175 mm		1	0
Dielectric 2	core	FR4	1.065 mm		4.5	0.02
+3.3	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR4	0.2 mm		4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Black	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

Benjamin Hüpeden
SmarHarz



Sheet:
File: BME688_Breadboard.kicad_pcb

Title: BME688 Breakout Board

Size: A4 Date: 2022-03-15

KiCad E.D.A. kicad (6.0.2)

Rev: 1.5

Id: 1/1